

**Amendment to the Abstract**

The invention related to a diode 2 comprising a connecting means (6) and a heat sink base (7). Said connecting (6) has a flat end (5) fixed on a die 16 and another end without fix shape. Said heat sink base (7) comprises: a base (18) which is at the bottom of said heat sink base (7); a press-fit region (4) which is set around said base (18); a solder platform (17) which is set above said base (18); a die (16) which has a first side and a second side electrically coupled to said flat-end (5) and said solder platform (17), respectively, and is fixed on said solder platform (17); a shoulder (12) which is extended acclivitously from said solder platform (17), the root of said shoulder connected to said solder platform 17 having a kink (13); and a cup (14) which is extended upwardly from the periphery of said base (18).